

Dummy	X (mm)	Y (mm)	Z (mm)	Mass (g)
nominal values	42.188	41.100	0.300	
1	42.235	41.135	0.313	1.242
2	42.235	41.137	0.307	1.244
3	42.238	41.136	0.307	1.242
4	42.237	41.138	0.315	1.244
5	42.239	41.138	0.314	1.244
6	42.240	41.137	0.317	1.243
7	42.240	41.138	0.323	1.250
8	42.240	41.137	0.315	1.249
9	42.235	41.137	0.320	1.248
10	42.234	41.139	0.320	1.247

We noticed that the X dimension is near or slightly out of the upper limit.

- Kapton tape measured at 50 μm
- HV hole covered before calibration
- Tool calibrated at 35 μm
- *We noticed that after calibration lowering the silicon jig and going back to contact position yield to a different height, usually 5 μm higher*
- **This procedure is wrong, see later. We should calibrate before applying kapton tape. Our effective calibration is around 80 μm**

Glue thickness and mass reproducibility without glass

Operator	Weight (mg)
Marco	68
Francesco	66
Marco	62
Thibaud	68
Paul	61
Thibaud	68
Paul	53

Notes

Glue mixed with a mixer for 2 min at 2000 rpm. Two series (Marco-Francesco, Thibaud-Paul). A series of attempts were done within 1 hr from glue mixing.

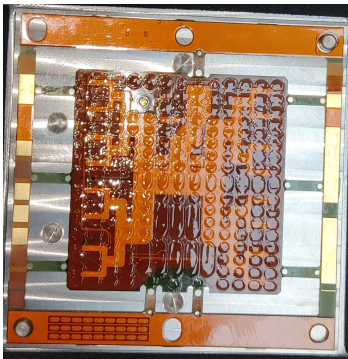


Figure 1: Glue deposition pattern after 20 min

First glue deposition after application on glass dummy and 20 min curing

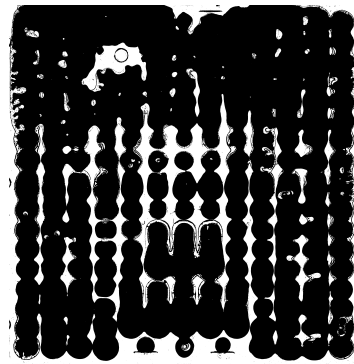
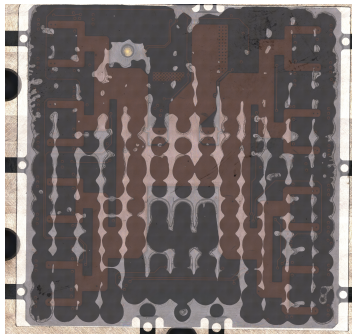


Figure 2: Glue deposition after glass

Estimated coverage from 1 bit map is 80%

After the photo the module is placed glass down on the CMT to measure pickup area heights.

Total height is $681.5 \mu\text{m}$. Glue thickness is $76.5 \mu\text{m}$. Glue mass 65 mg.

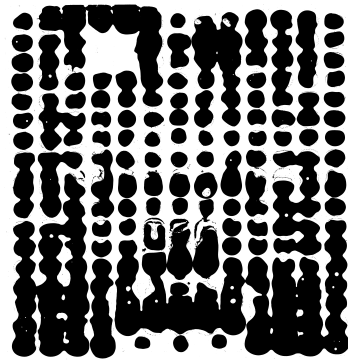
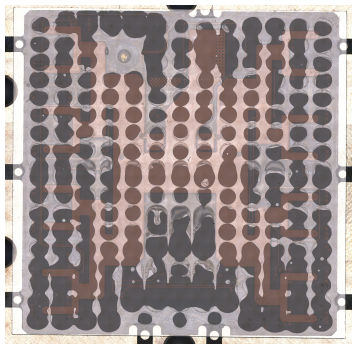


Figure 3: Glue distribution after full curing

Estimated coverage from 1 bit map is 57%

After the photo the module is placed glass down on the CMT to measure pickup area heights.

Total height is $687\text{ }\mu\text{m}$. Glue thickness is $82\text{ }\mu\text{m}$. Glue mass 66 mg.